ABSTRACT

METHODS TO PREVENT METAL DEPOSITED WAFERS FROM CONTAMINATING THE FRONT-END CLEANING SINKS OR FRONT END FURNACES

A new method and apparatus for detecting and measuring the level of metal present on the surface of a substrate is achieved. Energy, in the form of rf or light or microwave energy, is directed at the surface of a wafer, the reflected energy or the energy that passes through the semiconductor substrate is captured and analyzed for energy level and/or frequency content. Based on this analysis conclusions can be drawn regarding presence and type of metal on the surface of the wafer. Furthermore, by inclusion of metal within the resonating circuit of an rf generator changes the frequency of the vibration and therefore detects the presence of metal.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)